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APPLICATION NO.	1	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/064,766		08/15/2002	Chun-Ling Peng	8043-US-PA	9683
31561	7590	06/02/2005		EXAMINER	
•		TELLECTUAL PR	DEO, DUY VU NGUYEN		
7 FLOOR-1	•			ART UNIT	PAPER NUMBER
TAIPEI,	LI RUAL 100	), SECTION 2	1765		
TAIWAN	100			DATE MAILED: 06/02/200	r

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)					
•		10/064,766	PENG, CHUN-LING					
	Office Action Summary	Examiner	Art Unit					
		DuyVu n. Deo	1765					
Period f	The MAILING DATE of this communicat or Reply	ion appears on the cover sheet	with the correspondence address	-				
	ORTENED STATUTORY PERIOD FOR	REPLY IS SET TO EXPIRE 3	MONTH(S) FROM					
THE - Extending - If the - If N - Fail	MAILING DATE OF THIS COMMUNICA ensions of time may be available under the provisions of 37 or SIX (6) MONTHS from the mailing date of this communical e period for reply specified above is less than thirty (30) date of the provision of 37 or six (30) date of the provision of 37 or six (30) date of the period for reply is specified above, the maximum statutor that the period for reply will, or reply received by the Office later than three months after the patent term adjustment. See 37 CFR 1.704(b).	TION.  7 CFR 1.136(a). In no event, however, may ation.  9ys, a reply within the statutory minimum of the statutory minim	a reply be timely filed thirty (30) days will be considered timely. ONTHS from the mailing date of this communical ABANDONED (35 U.S.C. § 133).	ition.				
Status								
1)[\inf	Responsive to communication(s) filed o	n <i>01 April 2005</i> .						
		∑ This action is non-final.						
<u>'</u>	<b>'</b>		atters, prosecution as to the merits	s is				
· , <b>_</b>	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Disposi	tion of Claims		•					
4)⊠	Claim(s) 1-4 and 8-10 is/are pending in	the application.						
,—	4a) Of the above claim(s) is/are withdrawn from consideration.							
5)□	Claim(s) is/are allowed.	•						
	Claim(s) is/are rejected.							
7)								
<u> </u>	Claim(s) are subject to restriction	and/or election requirement.						
Applica	tion Papers	•						
91	The specification is objected to by the E	yaminer	·					
	The drawing(s) filed on is/are: a)		n hy the Examiner					
10/	Applicant may not request that any objection							
	Replacement drawing sheet(s) including the			1/d)				
11)		·						
Priority	under 35 U.S.C. § 119							
12)	Acknowledgment is made of a claim for	foreign priority under 35 U.S.C	8 119(a)-(d) or (f)					
	) ☐ All b) ☐ Some * c) ☐ None of:	ioroign phoney under co c.c.c	. 3 110(a) (a) 0; (i).					
<b>ω</b> .	1. Certified copies of the priority doc	cuments have been received						
	2. Certified copies of the priority doc		Application No					
	<u> </u>		en received in this National Stage					
	application from the International	•	on received in this radional otage					
*	See the attached detailed Office action for	` ''	ot received.					
Attachme	nt(s)							
	ce of References Cited (PTO-892)	4) Interview	w Summary (PTO-413)					
	ce of Draftsperson's Patent Drawing Review (PTO-	948) Paper N	lo(s)/Mail Date					
-	rmation Disclosure Statement(s) (PTO-1449 or PTC er No(s)/Mail Date	0/SB/08) 5) ☐ Notice of 6) ☐ Other: _	of Informal Patent Application (PTO-152)					

U.S. Patent and Trademark Office PTOL-326 (Rev. 1-04)

Application/Control Number: 10/064,766

Art Unit: 1765

## **DETAILED ACTION**

## Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-4, 8-10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Wu.

Wu describes a method for etching a substrate comprising: loading the substrate on a susceptor in an etching chamber (col. 2, line 30-35); performing etching with a height of the susceptor in the etching being adjusted to an different heights that results uniform and even etching of the material (col. 1, line 40-45; col. 3, line 16-40). The uniform and even etching would read on claimed minimum deviation of etching depth. Unlike claimed invention, Wu doesn't describe selecting the height resulting in a minimum deviation of etching depth as a height to perform a normal etching process. However, as suggested by Wu that different height would affect the etch rate differently over the substrate (col. 3, line 15-25); therefore, it would have been obvious for one skilled in the art to select a height that results in minimum deviation of etching depth because etching at one height would be easier, shorter, and simpler process than etching at different heights.

Referring to claim 9, the support pole 107 that moving up and down to adjust the height of the substrate would read on claimed shaft under the susceptor (col. 2, line 18-29).

Referring to claim 10, the material etched included oxide layer (col. 3, line 50-61). This would read on claimed silicon oxide layer.

Unlike claimed invention, Wu doesn't describe the etching method is for rounding a corner of an opening. However, he teaches that the method can be used with any etching process that requires uniform etching over the entire surface of the substrate (col. 4, line 59-63).

Therefore, it would have been obvious to one skilled in the art at the time of the invention to use the method for any etching including rounding corner of an opening in order to provide a uniform etching over the entire surface of the wafer.

## Response to Arguments

- Applicant's arguments with respect to claims 1-4, 8-10 have been considered but are most in view of the new ground(s) of rejection.
- 4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to DuyVu n Deo whose telephone number is 571-272-1462. The examiner can normally be reached on 6:00-3:30; with alternate Friday off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571-272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Primary Examiner Duy-Vu N. Deo 5/27/05